

# CSD95430RRB 同步降压 NexFET™ 智能功率级

## 1 特性

- 共享单个 PWM 输入的并联相位之间的主动电流平衡
- 峰值连续电流：90A
- 系统效率：电流为 30A 时大于 95%
- 高频运行：1.25MHz
- 二极管仿真功能，可实现高效的不连续导通模式 (DCM) 运行
- 温度补偿双向电流感应
- 模拟温度输出
- 故障监控
- PWM 信号兼容：3.3V 和 5V
- 三态 PWM 输入
- 集成自举开关
- 优化了击穿保护死区时间
- 高密度行业通用 QFN 5mm x 6mm 封装
- 超低电感封装
- 系统已优化的 PCB 空间占用
- 耐热增强型顶部散热
- 符合 RoHS 标准 - 无铅端子镀层
- 无卤素

## 2 应用

- 多相同步降压转换器
  - 大于 500A
  - 高频率
- 存储器和显卡
- 数据中心和网络交换机
- 校园网交换机和分支交换机
- 核心和边缘路由器
- 硬件加速器卡
- 高性能 CPU/ASIC/FPGA 电源

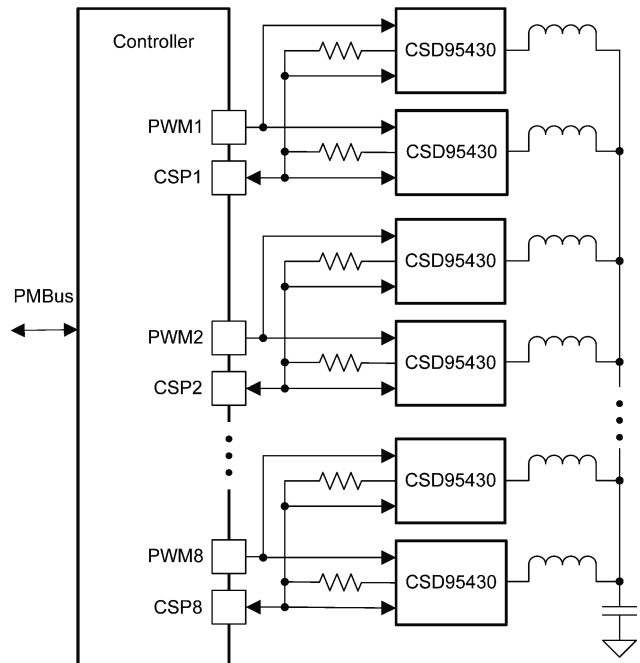
## 3 说明

CSD95430RRB NexFET™ 功率级是经过高度优化的设计，用于高功率、高密度同步降压转换器。此产品集成了驱动器 IC 和功率 MOSFET 以实现功率级开关功能。该组合采用 5mm × 6mm 小型封装，可实现高电流、高效率以及高速切换功能。它还集成了准确电流检测和温度感测功能，以简化系统设计并提高准确度。此外，PCB 封装已经过优化，可帮助减少设计时间并简化总体系统设计。该功率级具有主动电流平衡功能，允许多个功率级与单个 PWM 输入并联。这使得电流很高的应用的相位倍增成为可能，而无需类似的高相位数控制器。主动电流平衡功能确保倍增的相位均匀共享电流，因此并联相位时不需要显著降低电流能力。

### 器件信息

器件型号	封装 <sup>(1)</sup>	封装尺寸 (标称值)
CSD95430RRB	VQFN-CLIP	5.00 mm x 6.00 mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



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## 4 Revision History

注：以前版本的页码可能与当前版本的页码不同

DATE	REVISION	NOTES
January 2023	*	Initial release

## 5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 5.1 Documentation Support

#### 5.1.1 Related Documentation

### 5.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 5.3 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

### 5.4 Trademarks

NexFET™ and TI E2E™ are trademarks of Texas Instruments.

所有商标均为其各自所有者的财产。

### 5.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 5.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 6 Mechanical, Packaging, and Orderable Information

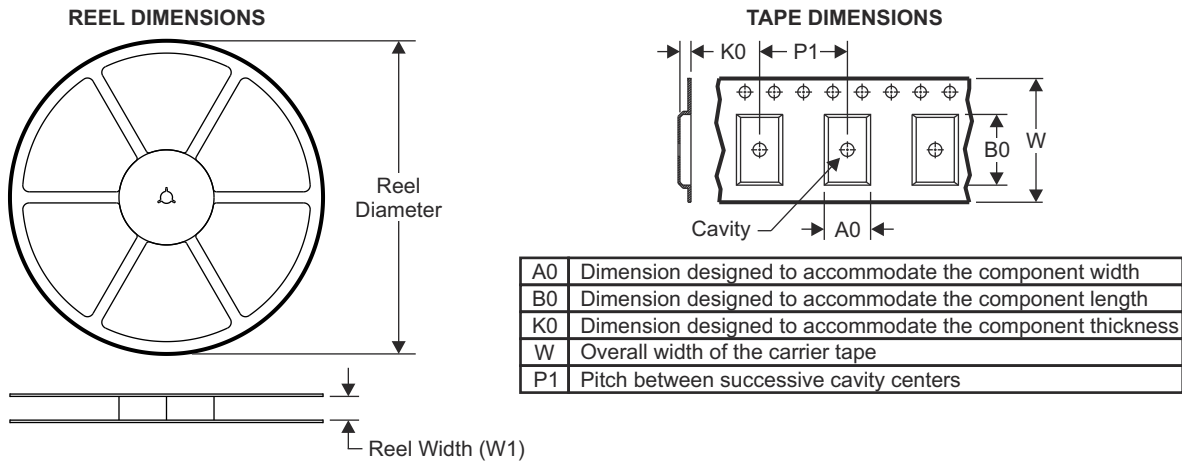
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## 6.1 Package Option Addendum

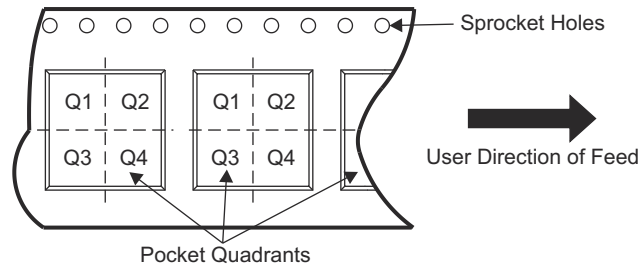
Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>	Op Temp (°C)	Device Marking <sup>(4) (5)</sup>
CSD95430RRB	ACTIVE	QFN	RRB	41	2500	RoHS-Exempt & Green	CU NIPDAU/ Matte-Tin	Level-2-260C-1 YEAR	- 55 to 150	95430RRB

- (1) The marketing status values are defined as follows:  
**ACTIVE:** Product device recommended for new designs.  
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.  
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.  
**PRE\_PROD** Unannounced device, not in production, not available for mass market, nor on the web, samples not available.  
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.  
**OBSOLETE:** TI has discontinued the production of the device.
- (2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.  
**TBD:** The Pb-Free/Green conversion plan has not been defined.  
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.  
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.  
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)
- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
- (5) Multiple Device markings will be inside parentheses. Only on Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.  
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.  
 In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## 6.2 Tape and Reel Information



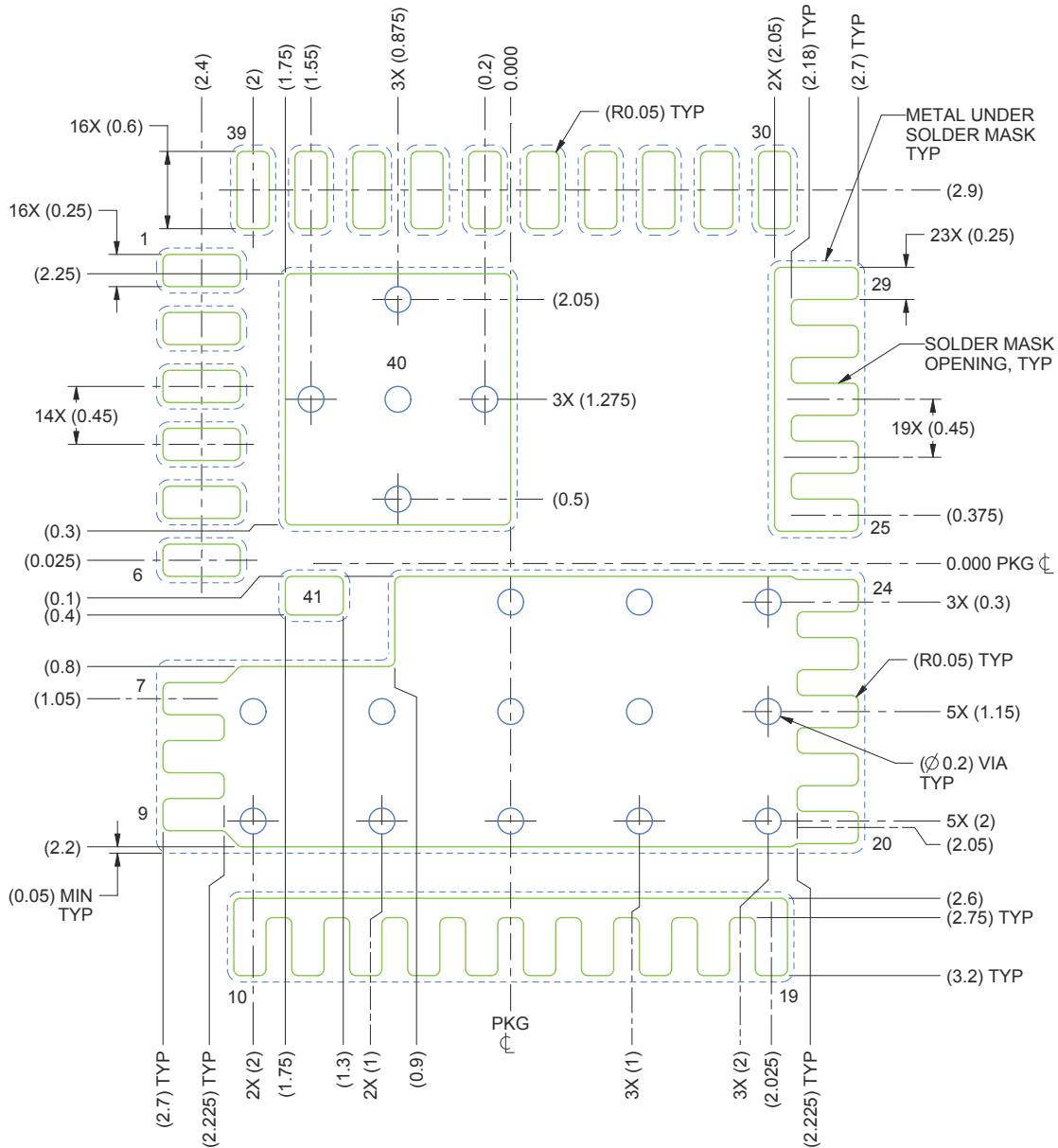
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD95430RRB	QFN	RRB	41	2500	330	12.4	5.30	6.30	1.20	8.00	12.0	Q1



## 6.4 Recommended PCB Land Pattern



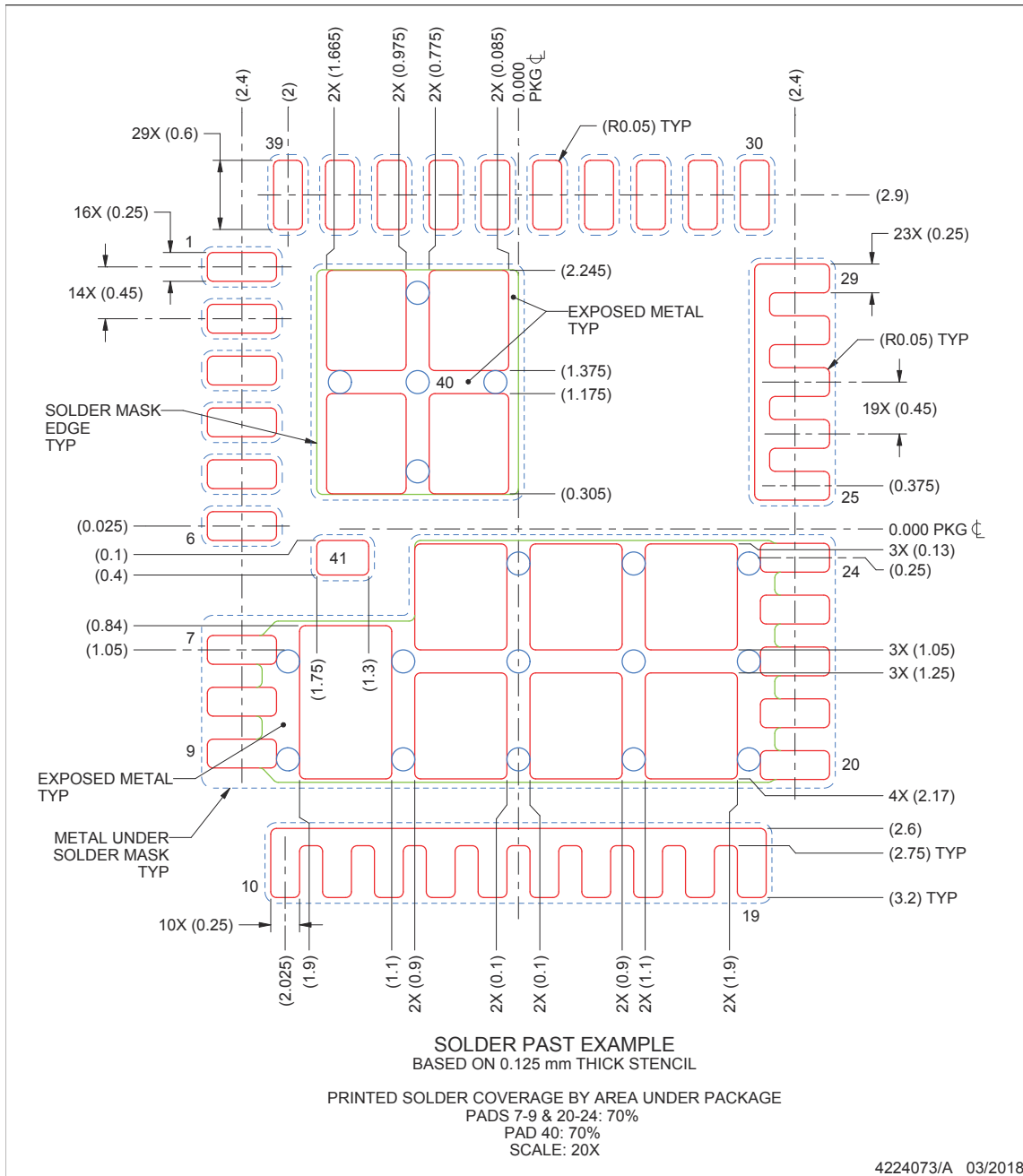
LAND PATTERN EXAMPLE  
SOLDER MASK DEFINED  
SCALE: 20X

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1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is designed to be soldered to thermal pads on the board. For more information, see [QFN/SOP PCB Attachment \(SLUA271\)](#).

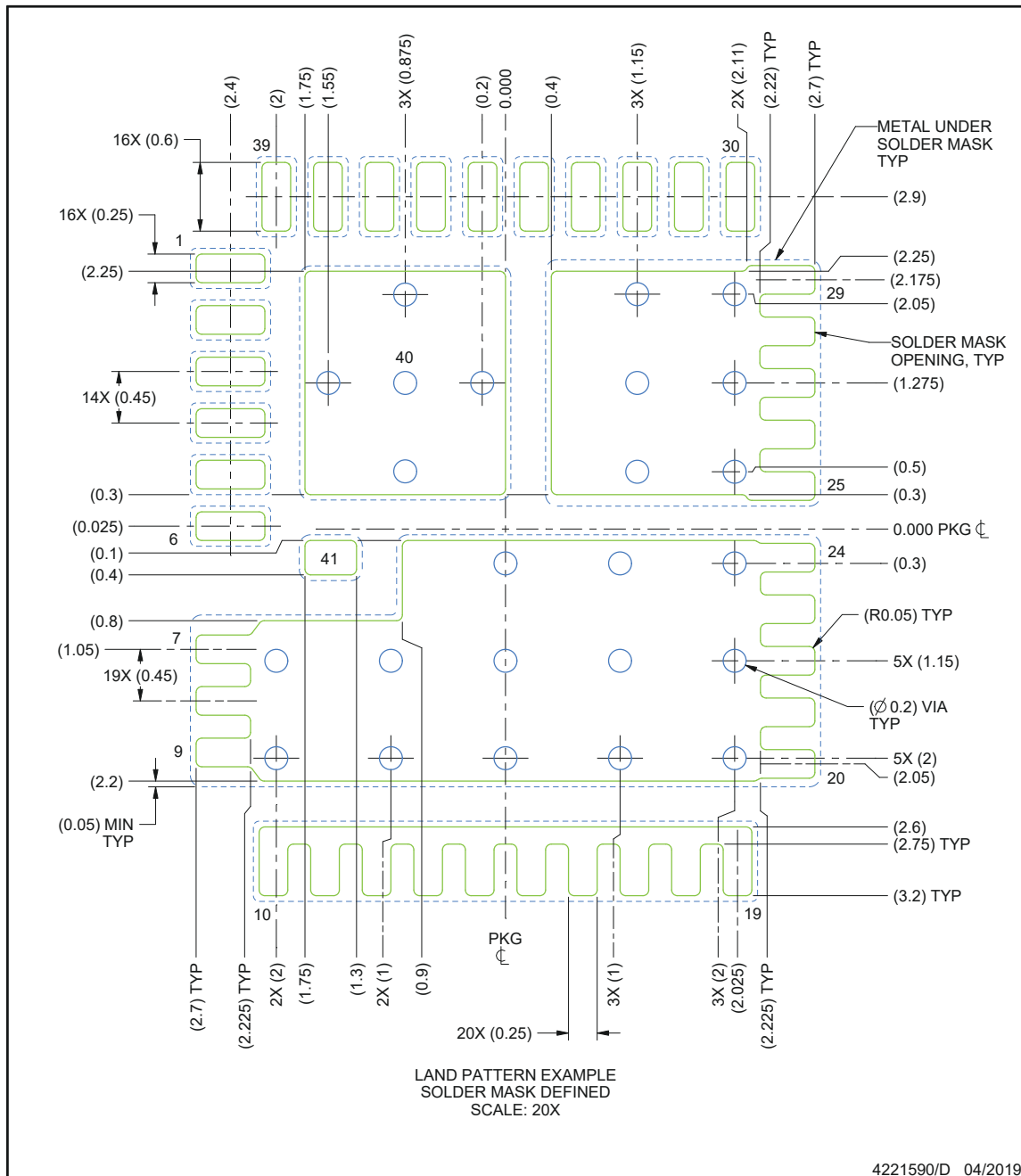


## 6.5 Recommended Stencil Opening



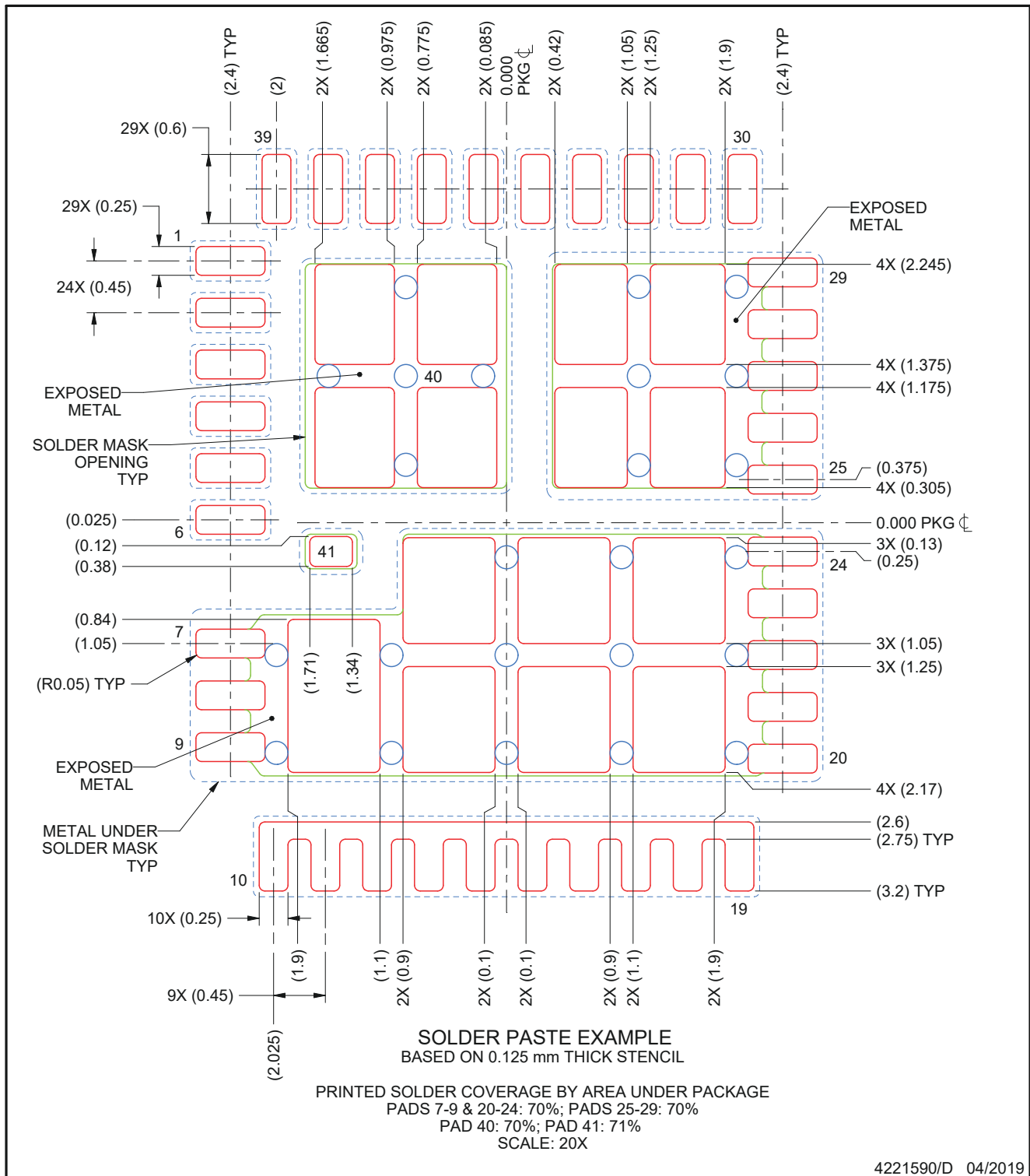
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 6.6 Alternate Industry Standard Compatible PCB Land Pattern



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

### 6.7 Alternate Industry Standard Compatible Stencil Opening



## 重要声明和免责声明

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